

# FMV19N60ES

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3S</sup> series

## **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (4.2±0.5V) High avalanche durability

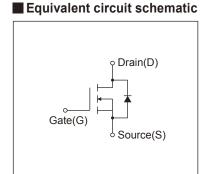
## Applications

Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

# Maximum Ratings and Characteristics

# ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

# ■ Outline Drawings [mm] TO-220F(SLS)



Description	Symbol	Characteristics	Unit	Remarks
Drain-Source Voltage	V <sub>DS</sub>	600	V	
Diain-Source voltage	VDSX	600	V	V <sub>GS</sub> = -30V
Continuous Drain Current	ID	±19	Α	
Pulsed Drain Current	IDP	±76	Α	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum AvalancheCurrent	IAR	19	Α	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	799	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	13	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	4.8	kV/µs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Maximum Dawar Dissination	P□	2.16	W	Ta=25°C
Maximum Power Dissipation		130	VV	Tc=25°C
Oneveting and Stevens Temperature venue	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to + 150	°C	
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz

### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250µA, V <sub>GS</sub> =0V	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>	I <sub>D</sub> =250μA, V <sub>DS</sub> =V <sub>GS</sub>		4.2	4.7	V
Zero Gate Voltage Drain Current		V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25	μА
	IDSS	V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		-	10	100	nA
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =9.5A, V <sub>GS</sub> =10V		-	0.31	0.365	Ω
Forward Transconductance	g <sub>fs</sub>	I <sub>D</sub> =9.5A, V <sub>DS</sub> =25V		8	16	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V V <sub>GS</sub> =0V f=1MHz		-	2700	4050	pF
Output Capacitance	Coss			-	300	450	
Reverse Transfer Capacitance	Crss			-	17	26	
Turn-On Time td(c	td(on)	Vcc=300V		-	45	68	ns
	tr	V <sub>GS</sub> =10V		-	35	53	
Turn-Off Time	td(off)	I <sub>D</sub> =9.5A R <sub>G</sub> =15Ω		-	122	183	
	tf			-	20	30	
Total Gate Charge	Q <sub>G</sub>	V -200V	14 00014		74	111	nC
Gate-Source Charge	QGS	- V <sub>∞</sub> =300V - I <sub>D</sub> =19A - V <sub>G</sub> =10V		-	23	34.5	
Gate-Drain Charge	Q <sub>GD</sub>			-	25	38	
Gate-Drain Crossover Charge	Qsw			-	9	14	
Avalanche Capability	lav	L=1.71mH, Tch=25°C	L=1.71mH, Tch=25°C		-	-	Α
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =19A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.90	1.35	V
Reverse Recovery Time	trr	I <sub>F</sub> =19A, V <sub>GS</sub> =0V		-	0.6	-	μS
Reverse Recovery Charge	Qrr	-di/dt=100A/μs, Tch=25°C		-	10	-	μC

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to case			0.960	°C/W
	Rth (ch-a)	Channel to ambient			58.0	°C/W

Note \*1 : Tch≤150°C

Note \*2: Stating Tch=25°C, Ias=8A, L=22.9mH, Vcc=60V, R<sub>G</sub>=50Ω

Eas limited by maximum channel temperature and avalanche current.

See to 'Avalanche Energy' graph.

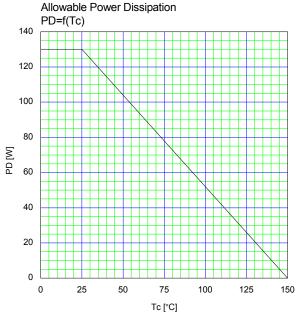
Note  $^{\star}3$  : Repetitive rating : Pulse width limited by maximum channel temperature

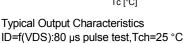
See to the 'Transient Themal impeadance' graph.

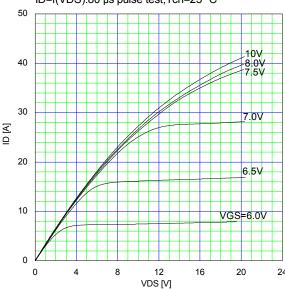
Note \*4 : Ir≤-Ip, -di/dt=100A/µs, Vcc≤BVbss, Tch≤150°C.

Note \*5 : Ir≤-Ip, dv/dt≤4.8kV/µs, Vcc≤BVbss, Tch≤150°C.

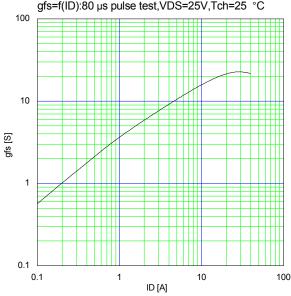
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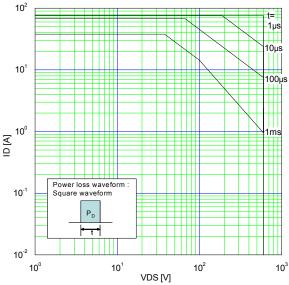




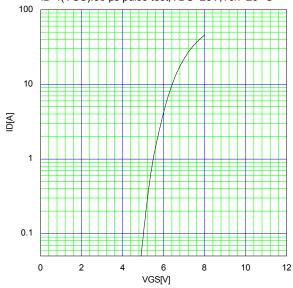
Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25 °C



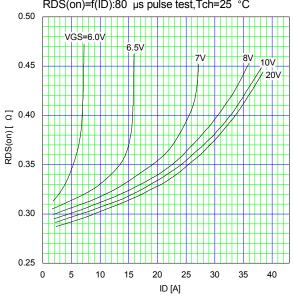
Safe Operating Area  $I_D=f(V_{DS})$ :Duty=0(Single pulse),Tc=25 °c



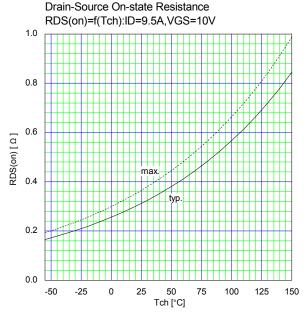
Typical Transfer Characteristic ID=f(VGS):80 µs pulse test,VDS=25V,Tch=25 °C



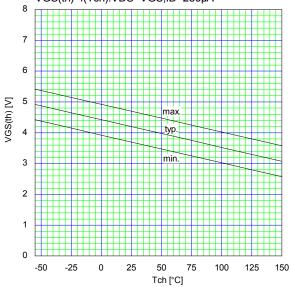
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25 °C



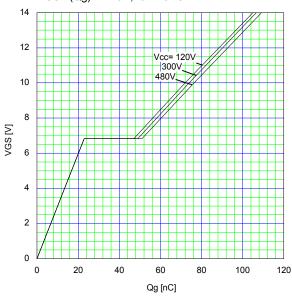
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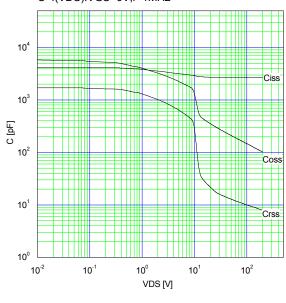
Gate Threshold Voltage vs. Tch VGS(th)=f(Tch):VDS=VGS,ID=250µA



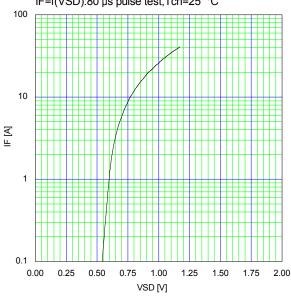
Typical Gate Charge Characteristics VGS=f(Qg):ID=19A,Tch=25 °C



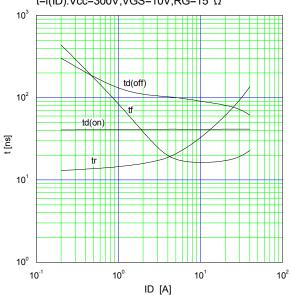
Typical Capacitance C=f(VDS):VGS=0V,f=1MHz

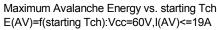


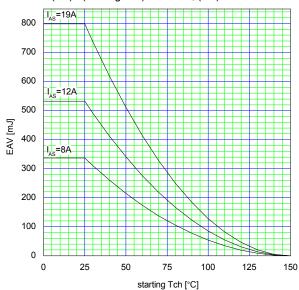
Typical Forward Characteristics of Reverse Diode IF=f(VSD):80  $\mu$ s pulse test,Tch=25 °C

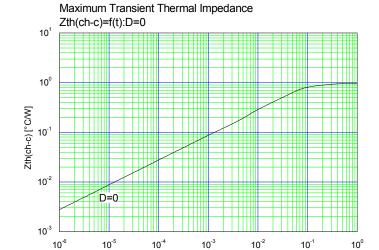


Typical Switching Characteristics vs. ID t=f(ID):Vcc=300V,VGS=10V,RG=15  $\Omega$ 









t [sec]

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